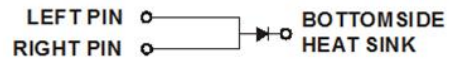
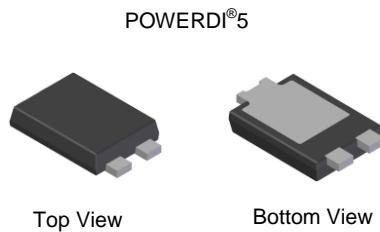


Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Low Forward Voltage Drop
- For Use in Low-Voltage, High-Frequency Inverters, Free Wheeling, and Polarity Protection Applications
- High Forward Surge Current Capability
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: POWERDI®5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (e3)
- Polarity: See Diagram
- Weight: 0.093 grams (Approximate)



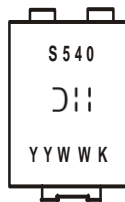
Note: Pins Left & Right must be electrically connected at the printed circuit board.

Ordering Information (Note 4)

| Part Number | Case | Packaging |
|---------------------|-----------|-------------------|
| PDS540-13 | POWERDI®5 | 5,000/Tape & Reel |
| PDS540-13D (Note 5) | POWERDI®5 | 5,000/Tape & Reel |

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.
 5. Suffix -13D is designated for 12mm tape width.

Marking Information



- S540 = Product Type Marking Code
- D I I = Manufacturers' Code Marking
- YYWW = Date Code Marking
- YY = Last Digit of Year (ex: 15 for 2015)
- WW = Week Code (01 – 53)
- K = Factory Designator

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

| Characteristic | Symbol | Value | Unit |
|---|---------------------|-------|------|
| Peak Repetitive Reverse Voltage | V _{RRM} | 40 | V |
| Working Peak Reverse Voltage | V _{RWM} | | |
| DC Blocking Voltage | V _R | | |
| RMS Reverse Voltage | V _{R(RMS)} | 28 | V |
| Average Rectified Output Current | I _O | 5 | A |
| Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave Superimposed on Rated Load | I _{FSM} | 150 | A |

Thermal Characteristics

| Characteristic | Symbol | Typ | Max | Unit |
|---|-----------------------------------|-------------|-----|------|
| Thermal Resistance Junction to Soldering Point | R _{θJS} | — | 4.0 | °C/W |
| Thermal Resistance Junction to Ambient Air (Note 6) | R _{θJA} | 90 | — | °C/W |
| Thermal Resistance Junction to Ambient Air (Note 7) | R _{θJA} | 65 | — | °C/W |
| Thermal Resistance Junction to Ambient Air (Note 8) | R _{θJA} | 50 | — | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -65 to +150 | | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|------------------------------------|--------------------|-----|-------|------|------|---|
| Reverse Breakdown Voltage (Note 9) | V _{(BR)R} | 40 | — | — | V | I _R = 0.5mA |
| Forward Voltage | V _F | — | 0.48 | 0.52 | V | I _F = 5A, T _S = +25°C |
| | | — | 0.43 | 0.47 | | I _F = 5A, T _S = +125°C |
| | | — | 0.57 | 0.65 | | I _F = 10A, T _S = +25°C |
| | | — | 0.55 | 0.59 | | I _F = 10A, T _S = +125°C |
| Reverse Leakage Current (Note 9) | I _R | — | 0.015 | 0.25 | mA | T _S = +25°C, V _R = 40V |
| | | — | 3 | 15 | | T _S = +100°C, V _R = 40V |
| | | — | 10 | 40 | | T _S = +125°C, V _R = 40V |

- Notes:
6. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
 7. Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
 8. Polyimide PCB, 2 oz. Copper. Cathode pad dimensions 9.4mm x 7.2mm. Anode pad dimensions 2.7mm x 1.6mm.
 9. Short duration pulse test used to minimize self-heating effect.

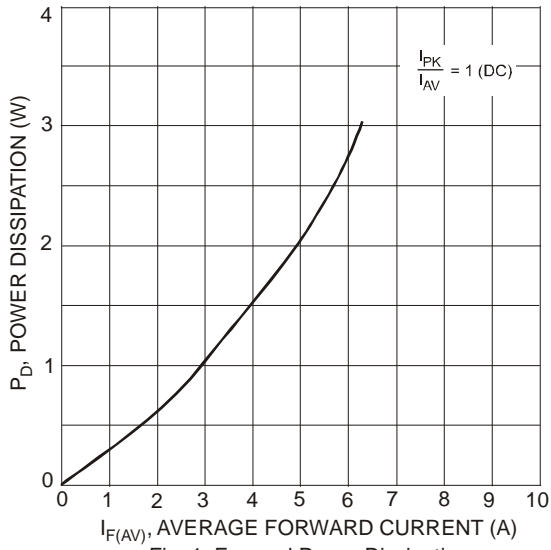


Fig. 1 Forward Power Dissipation

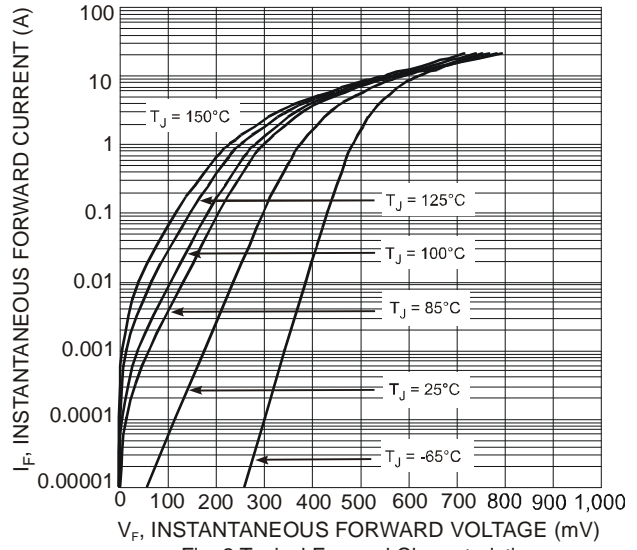


Fig. 2 Typical Forward Characteristics

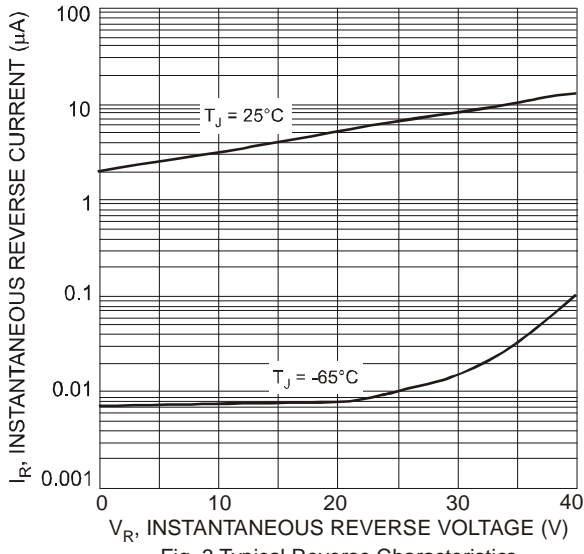


Fig. 3 Typical Reverse Characteristics

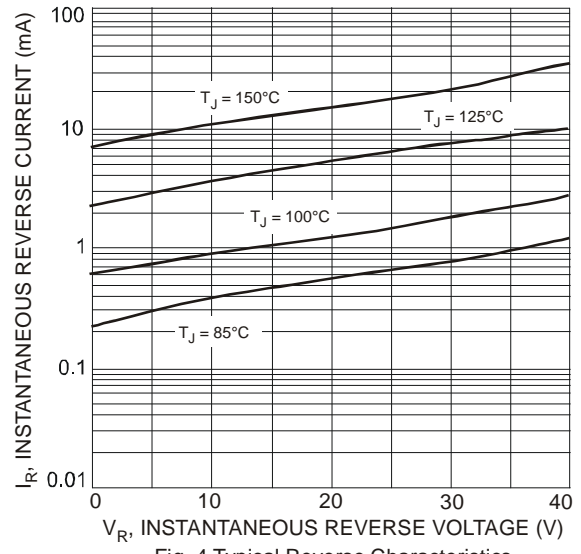


Fig. 4 Typical Reverse Characteristics

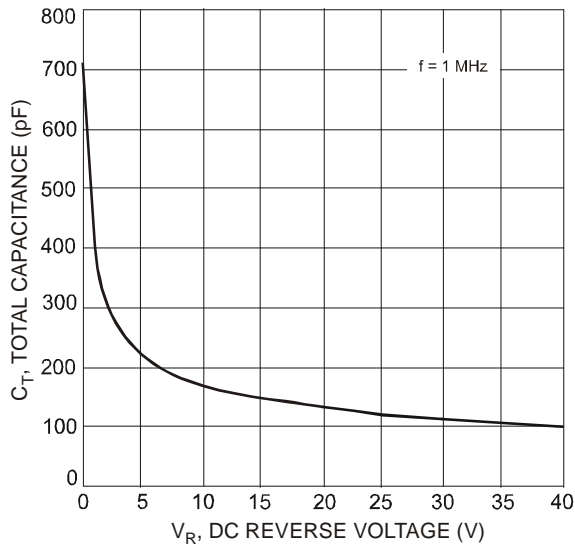


Fig. 5 Total Capacitance vs. Reverse Voltage

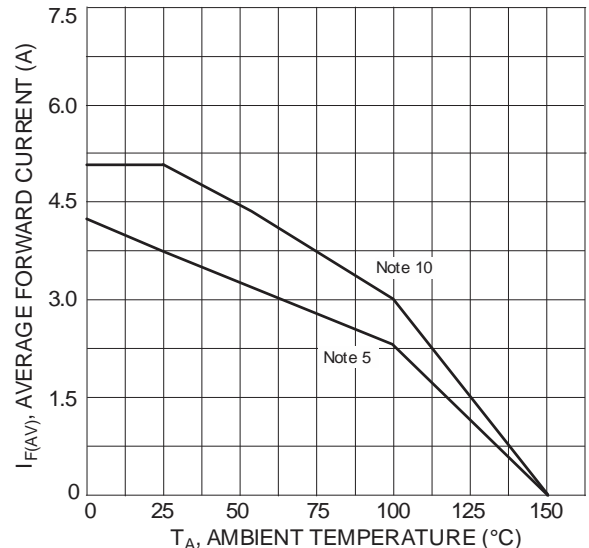


Fig. 6 Forward Current Derating Curve

Note: 10. Polyimide PCB, 2 oz. Copper. Cathode pad dimensions 6.5mm x 5.0mm. Anode pad dimensions 1.8mm x 1.1mm.

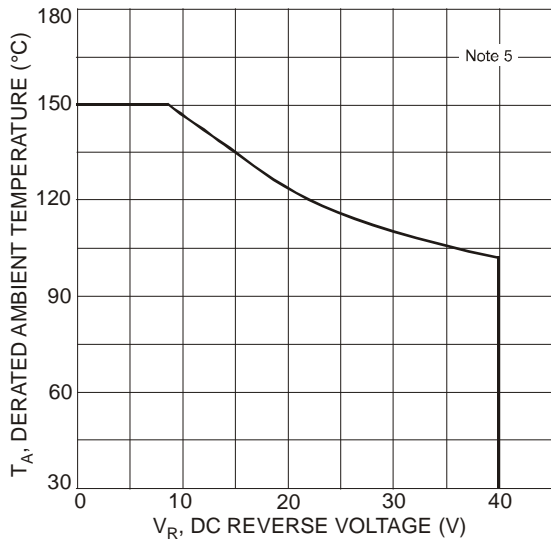
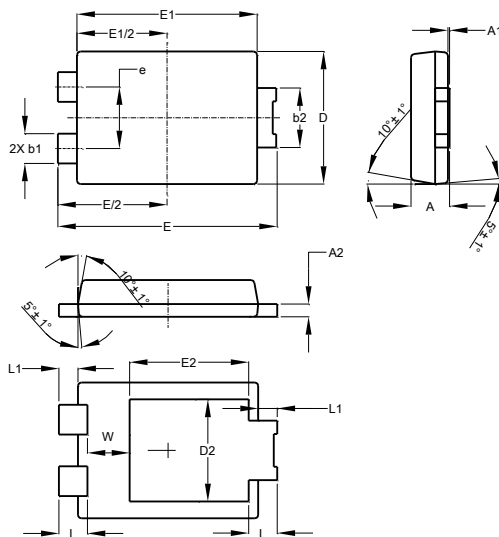


Fig. 7 Operating Temperature Derating

Package Outline Dimensions

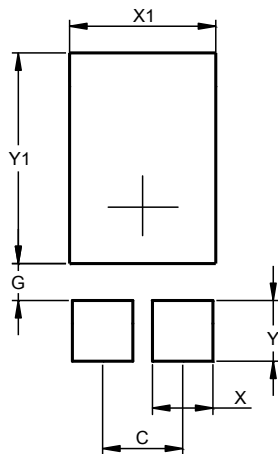
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



| POWERDI [®] 5 | | | |
|------------------------|------|------|-------|
| Dim | Min | Max | Typ |
| A | 1.05 | 1.15 | 1.10 |
| A1 | 0.00 | 0.05 | -- |
| A2 | 0.33 | 0.43 | 0.381 |
| b1 | 0.80 | 0.99 | 0.89 |
| b2 | 1.70 | 1.88 | 1.78 |
| D | 3.90 | 4.05 | 3.966 |
| D2 | -- | -- | 3.054 |
| E | 6.40 | 6.60 | 6.504 |
| e | -- | -- | 1.84 |
| E1 | 5.30 | 5.45 | 5.37 |
| E2 | -- | -- | 3.549 |
| L | 0.75 | 0.95 | 0.85 |
| L1 | 0.50 | 0.65 | 0.57 |
| W | 1.10 | 1.41 | 1.255 |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 1.840 |
| G | 0.852 |
| X | 1.390 |
| X1 | 3.360 |
| Y | 1.400 |
| Y1 | 4.860 |

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